Variant: 001
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TID #: TIDA-01486

TIDA-01486 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB	1		TIDA-01486	Any	Printed Circuit Board	
2	C1, C2, C3, C4	4	1000pF	GRM188R71H102JA01D	MuRata	CAP, CERM, 1000 pF, 50 V,+/- 5%, X7R, 0603	0603
3	C9, C10, C11, C12, C13, C14, C15, C16, C17, C18, C19, C20, C39, C41, C43, C45, C55, C56, C57, C58	20	0.1uF	GRM155R71E104KE14D	MuRata	CAP, CERM, 0.1 µF, 25 V,+/- 10%, X7R, 0402	0402
4	C23, C24, C25, C26	4	1000pF	GRM1885C1H102FA01J	MuRata	CAP, CERM, 1000 pF, 50 V,+/- 1%, C0G/NP0, 0603	0603
5	C27, C28, C29, C30, C31, C32, C33, C34, C35, C36, C37, C38, C40, C42, C44, C46	16	6.8uF	TPSA685K020R1000	AVX	CAP, TA, 6.8 µF, 20 V, +/- 10%, 1 ohm, SMD	3216-18
6	C47, C48, C49, C50	4	1uF	GMK107AB7105KAHT	Taiyo Yuden	CAP, CERM, 1 µF, 35 V,+/- 10%, X7R, AEC-Q200 Grade 0, 0603	0603
7	D1, D2, D3, D4	4	30V	DFLS130L-7	Diodes Inc.	Diode, Schottky, 30 V, 1 A, PowerDI123	PowerDI123
8	D5, D6, D7, D8, D9, D10, D11, D12, D13, D14, D15, D16	12	100V	1N4148W-7-F	Diodes Inc.	Diode, Ultrafast, 100 V, 0.15 A, SOD-123	SOD-123
9	J1, J2	2		SSW-110-23-F-S	Samtec	Connector, Receptacle, 100mil, 10x1, Gold plated, TH	10x1 Receptacle
10	J3, J4	2		TSW-104-07-G-D	Samtec	Header, 100mil, 4x2, Gold, TH	4x2 Header
11	J5, J6	2		TSW-103-07-G-S	Samtec	Header, 100mil, 3x1, Gold, TH	3x1 Header
12	J7	1		TSW-102-07-G-S	Samtec	Header, 100mil, 2x1, Gold, TH	2x1 Header
13	LBL1	1		THT-14-423-10	Brady	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650 x 0.200 inch
14	R1, R2, R3, R4	4	1.00k	RC0603FR-071KL	Yageo America	RES, 1.00 k, 1%, 0.1 W, 0603	0603
15	R5, R6, R7, R8, R13, R14, R15, R16	8	866	CRCW0603866RFKEA	Vishay-Dale	RES, 866, 1%, 0.1 W, 0603	0603
16	R9, R10, R11, R12, R17, R18, R19, R20	8	95.3	CRCW060395R3FKEA	Vishay-Dale	RES, 95.3, 1%, 0.1 W, 0603	0603
17	R21, R22, R23, R24	4	100k	RT0603BRD07100KL	Yageo America	RES, 100 k, 0.1%, 0.1 W, 0603	0603
18	R25, R26, R27, R28	4	24.9k	RT0603BRD0724K9L	Yageo America	RES, 24.9 k, 0.1%, 0.1 W, 0603	0603
19	R29, R30, R31, R32	4	0	RMCF0603ZT0R00	Stackpole Electronics Inc	RES, 0, 1%, 0.1 W, AEC-Q200 Grade 0, 0603	0603
20	R35, R36, R37, R38	4	200	CRCW0402200RFKED	Vishay-Dale	RES, 200, 1%, 0.063 W, 0402	0402
21	R39, R40, R41, R42	4	10	CRCW060310R0JNEAHP	Vishay-Dale	RES, 10, 5%, 0.25 W, 0603	0603
22	R43, R44	2	10k	CRCW040210K0JNED	Vishay-Dale	RES, 10 k, 5%, 0.063 W, 0402	0402
23	U1, U2, U3, U4, U5, U6, U7, U8	8		THS3095D	Texas Instruments	Single-High-Voltage, Low Distortion, Current-Feedback Operational Amplifier with Power-Down, 10 to 30 V, -40 to 85 degC, 8-pin SOIC (D8), Green (RoHS & no Sb/Br)	D0008A
24	U9, U10, U11, U12	4		TS5A3357DCUR	Texas Instruments	Single 5-Ohm SP3T Analog Switch 5-V/3.3-V 3:1 Analog Multiplexer/Demultiplexer, DCU0008A (VSSOP-8)	DCU0008A
25	U13	1		SN74LVC1G08DBVR	Texas Instruments	Single 2-Input Positive-AND Gate, DBV0005A, LARGE T&R	DBV0005A
26	C51, C52, C53, C54	0	2.2uF	EMK107BB7225MA-T	Taiyo Yuden	CAP, CERM, 2.2 µF, 16 V,+/- 10%, X7R, 0603	0603
27	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	N/A

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